



N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)		
30	0.034 at V _{GS} = 10 V	7.8	4 nC		
	0.052 at V _{GS} = 4.5 V	6.3	4110		

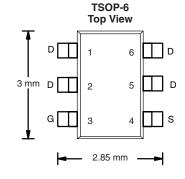
FEATURES

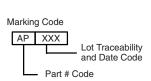
- Halogen free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

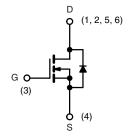


APPLICATIONS

- · Load Switch
- HDD







Ordering Information: Si3456CDV-T1-E3 (Lead (Pb)-free)

Si3456CDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 20		
	T _C = 25 °C		7.7		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	1 , [6.2		
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	l _D	6.1 ^{a, b}		
	T _A = 70 °C	1	4.9 ^{a, b}	Α	
Pulsed Drain Current		I _{DM}	20		
Continuous Source-Drain Diode Current	T _C = 25 °C	,	2.9		
	T _A = 25 °C	l _S	1.7 ^{a, b}		
	T _C = 25 °C		3.3		
Maximum Power Dissipation	T _C = 70 °C		2.1	w	
	T _A = 25 °C	P _D	2 ^{a, b}	VV	
	T _A = 70 °C	1	1.3 ^{a, b}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature)			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 5 s	R _{thJA}	53	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	32	38		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 110 °C/W.
- d. Based on $T_C = 25$ °C.

Si3456CDV

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						1	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			٧	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 ·· A		30		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.2		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 70 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	15			Α	
Drain-Source On-State Resistance ^a	, ,	V _{GS} = 10 V, I _D = 6.1 A		0.028	0.034	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 1.9 \text{ A}$		0.043	0.052		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 6.1 A		12		S	
Dynamic ^b							
Input Capacitance	C _{iss}			460			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		85		pF	
Reverse Transfer Capacitance	C _{rss}			45			
Total Gate Charge	Qg	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 6.1 A		8	12	nC	
				4	6		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 6.1 \text{ A}$		1.8			
Gate-Drain Charge	Q_{gd}			1.2			
Gate Resistance	R_{g}	f = 1 MHz	2.4	4.8	7.2	Ω	
Turn-On Delay Time	t _{d(on)}			20	30	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3.1 Ω		12	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4.9~A,~V_{GEN}=4.5~V,~R_g=1~\Omega$		15	25		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = 15 V, R_L = 3.1 Ω		12	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4.9~A,~V_{GEN}=10~V,~R_g=1~\Omega$		12	20		
Fall Time	t _f			10	15		
Drain-Source Body Diode Characteristic	cs				•		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.9	Δ	
Pulse Diode Forward Current	I _{SM}				20	Α .	
Body Diode Voltage	V_{SD}	I _S = 2.5 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			20	30	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 4.9 A, dI/dt = 100 A/μs, T _J = 25 °C		12	20	nC	
Reverse Recovery Fall Time	t _a	1 = 4.3 A, α/αι = 100 A/μs, 1 J = 25 C		13		no	
Reverse Recovery Rise Time	t _b			8		ns	

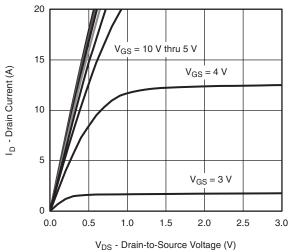
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

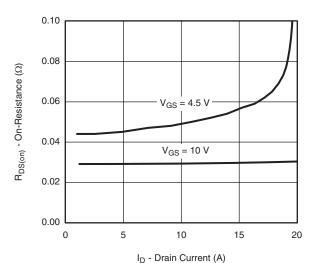




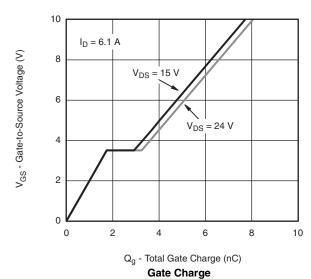
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

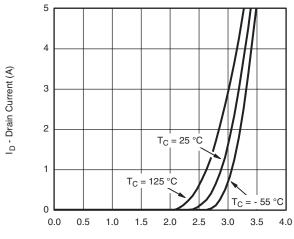


Output Characteristics



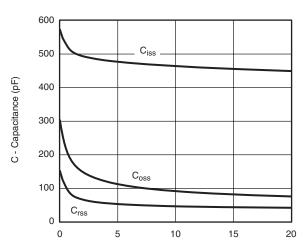
On-Resistance vs. Drain Current and Gate Voltage





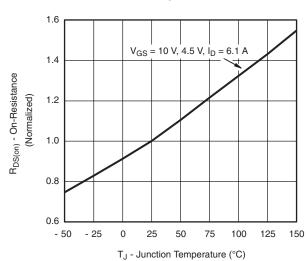
V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



V_{DS} - Drain-to-Source Voltage (V)

Capacitance

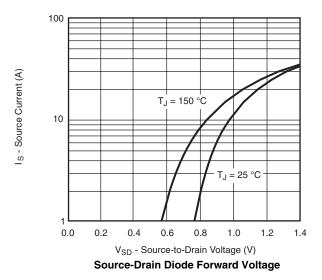


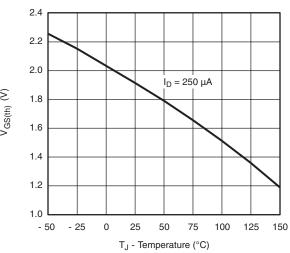
On-Resistance vs. Junction Temperature

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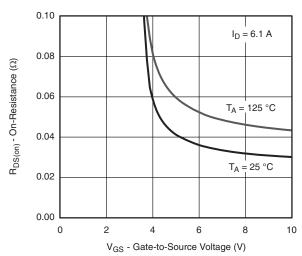
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

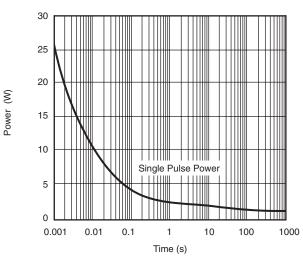




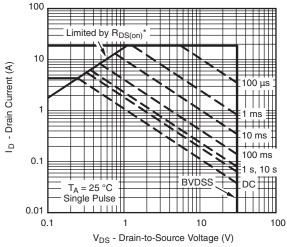
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



* V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

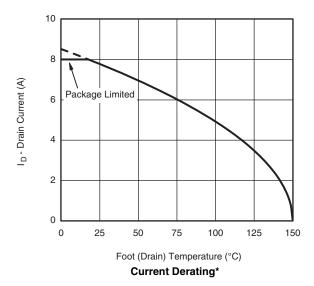
Safe Operating Area, Junction-to-Ambient

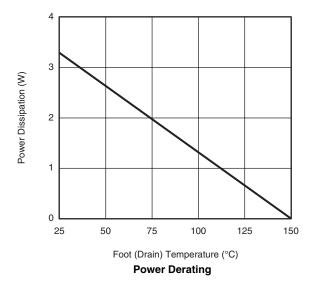




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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



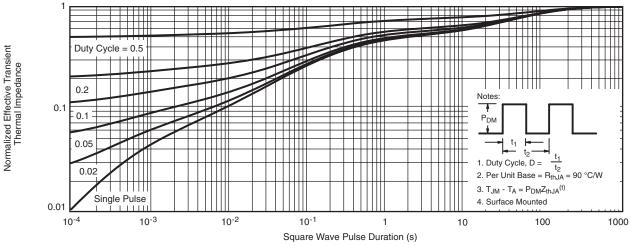


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

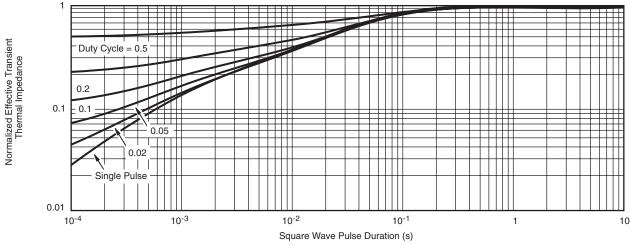
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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